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(19) **United States**(12) **Patent Application Publication**
Li et al.(10) **Pub. No.: US 2022/0353991 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **STACKABLE MEMORY MODULE WITH
DOUBLE-SIDED COMPRESSION CONTACT
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(57)

ABSTRACT

An example of an apparatus may comprise a first set of compression contact pads formed on a first side of a circuit board, a second set of compression contact pads formed on a second side of the circuit board opposite to the first side of the circuit board, where the first set of compression contact pads are respectively electrically connected to the second set of compression pads. An example of the circuit board may include a memory board. An example stackable memory module may include memory devices mounted to both sides of the memory board. Other examples are disclosed and claimed.

